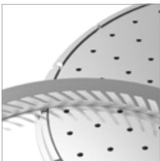
ADVANCED PACKAGING

Take Advanced Packaging to a completely new level.



As functionality and reliability of electronic devices progress, requiring changes in systems development and integration, materials, chemicals and auxiliaries are undergoing significant adaptions in performance, cost-efficiency and reliability.

In order to respond to such market needs, Umicore´s business unit Metal Deposition Solutions has partnered with Shinhao Materials to provide innovative patented additives for copper electroplating in the advanced packaging industry together with Umicore´s Copper(II)oxide and Electrode solutions for ECD tools.

www.mds.umicore.com
www.shinhaomaterials.com

IntraCu® Electrolytes

IntraCu® SC-2

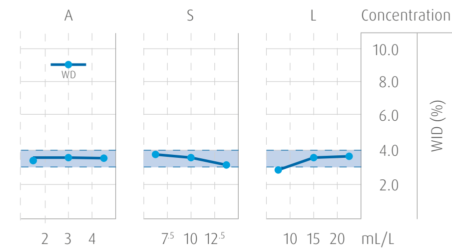
System provides customers the opportunity to reduce total cost of ownership by extending their process window. In addition, it is a true 2in1 procedure that produces no or only a small number of Kirkendall-voids (KV-less). The system is a drop-in replacement for current POR offerings.

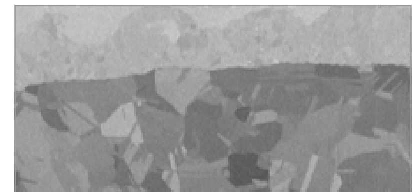
SYSTEM FEATURES

- Bright Cu, Ra < 0.03 µm
- ±50% process window for Cu pillar and RDL
- Total in-film organics < 11 ppm
- Excellent KV-less performance

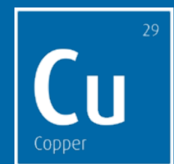
SYSTEM APPLICATIONS

- 2-in-1 bright Cu (Cu pillar and RDL)
- 2-in-1 with KV-less requirement



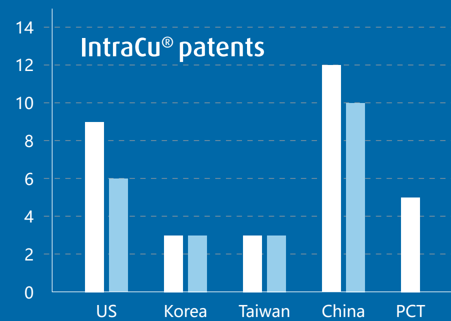


1000 hrs @ 175 C



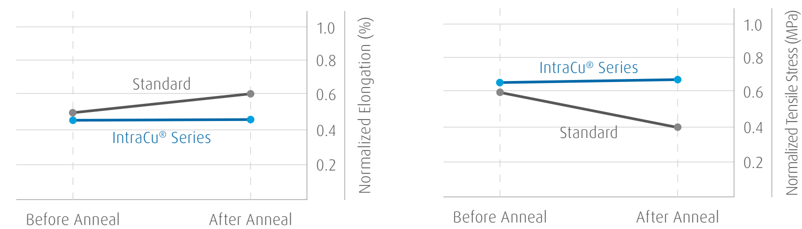
Our modular additives are designed to meet the highest requirements of the semiconductor industry in advanced packaging and offer the foundation for depositing customized material properties e.g. for Microbumps in IC packages, RDL in wafer level packaging and Pillar in flip-chip packaging

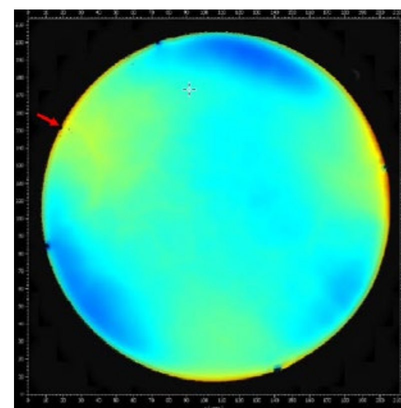
Patent Applications Issued Patents



IntraCu® SC-6

System provides customers the opportunity to make products that require thermal and mechanical stability in future, so that fine lines/structures will not break during subsequent packaging and assembly operations. Especially for TAIKO wafers the process ensures no warping/damage. On glass or ceramic substrates IntraCu SC 6 Cu layers provides best adhesion due low internal stress of the Copper layer.

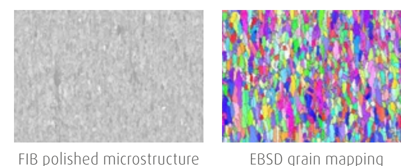




No/low stress of IntraCu® SC layers: 8 inch blanket wafer, plated on one side with 20 µm, warpage < 10 µm.

IntraCu® SC-4

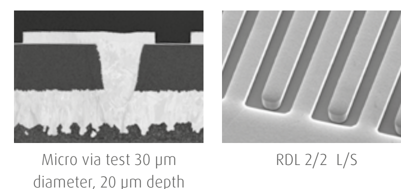
System has be specially designed for addressing morphological requirements for "Cu2Cu direct bonding" in 3D due the unique grain structure obtained. Its morphology remains largely unchanged after thermal excursions providing the basis for best pad height uniformity to allow further interconnect pitch scaling in W2W bonding.



FIB polished microstructure EBSD grain mapping

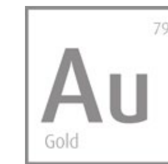
IntraCu® VF-9

A Cu plating process for simultaneously filling blind vias and reproducing fine-line RDL with outstanding thickness distribution particularly designed for PLP application.



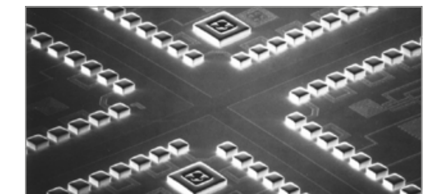
Micro via test 30 µm diameter, 20 µm depth RDL 2/2 L/S

Umicore Electrolytes



Umicore AURUNA® SC

A cyanide-free gold electroplating electrolyte for plating Gold with a purity of 99.99 %. The process is suitable for fine-pitched RDL wafers and Bump Plating. With the neutral pH range AURUNA® is compatible with most common resist types for this application. The process offer a very wide current density range and is very stable (up to 1.2 A/dm²).



Bump plating on test structure

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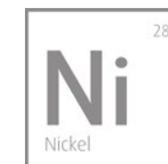
Metal Deposition Solutions



Umicore NiRUNA® SC

A sulfamate based system with very low stress, boric acid free version available.

Umicore ARGUNA® SC

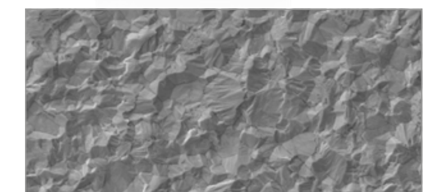
Is a mild alkaline cyanide-free pure Silver plating. ARGUNA® layers exhibit purity > 99 % providing resistivity and solderability in cyanide systems. The process features a wide compatibility with most resist types.

Umicore Tin SC

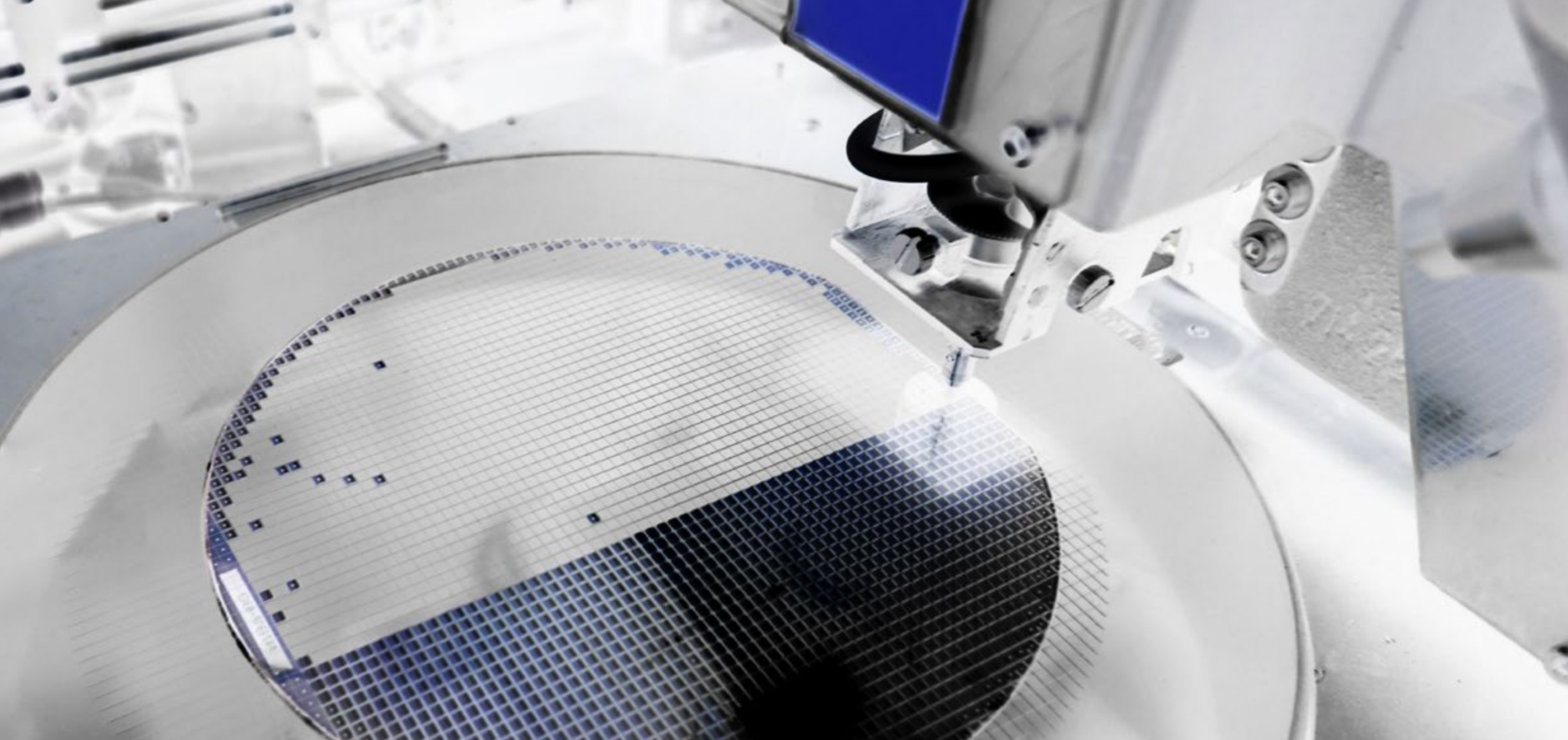
Pure Sn plating process operate with a wide current density range. The Sn coatings are very pure and have low tendency for whisker growth. Very stable electrolyte system based on MSA.

Umicore Indium SC

Umicore Indium SC systems deposit pure Indium layers over a very wide current density range. The stable electrolyte system is fully analysable and shows very good covering properties and uniform grain size.

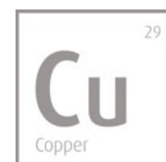


Typical grain structure Umicore Indium SC



ADVANCED PACKAGING

PRODUCTS FOR PERFECT ELECTROCHEMICAL DEPOSITION IN THE SEMICONDUCTOR INDUSTRY



Cu(II)Oxide high purity metal salt

	Umicore CuO PG	Umicore CuO HG	Umicore CuO 4N
Application	RDL and panel level substrates	Panel substrates	Fine line RDL and Pillar
Purity	99,9 %	99,9%	99,99%
auto-dosing compatibility DMR	✓	-	✓
Dissolution speed	★	★	★★
High Speed Plating	✓	✓	✓
Clean room packed / compatible	✓	-	✓

Picture: Courtesy ancosys GmbH

Umicore copper oxide high purity metal oxide powder are developed, manufactured and quality tested in accordance with the demanding requirements of the semiconductor advanced packaging industry. In combination with ancosys DMR® concept (Direct Metal Replenishment) clean room usage is possible enabling lower cost of ownership for Cu replenishment along with a boost in performance of the electrolyte through higher Cu concentrations.

NO VMS NEEDED

- H_2SO_4 concentration remaining consistent. Stable electrolyte volume, feed and bleed not needed.
- Several grades (4N, Packaging)
- Full traceability, only one source for Cu

COST EFFICIENCY

- Reduction tool down time, supporting maintenance-free plating chambers
- 50% lower cost per kg Cu compared with VMS
- 15% higher speed through higher Cu^{2+} (60g/l i/o 50g/l)

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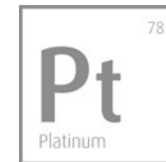
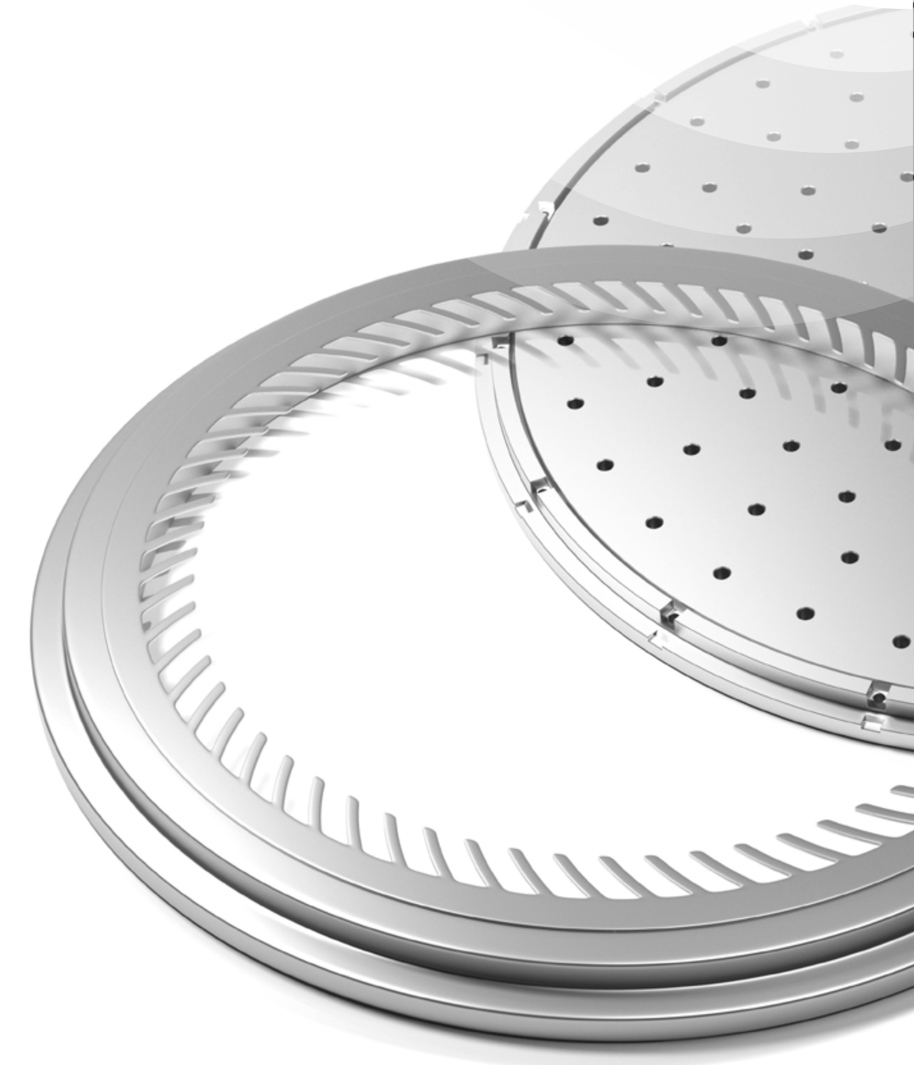
Metal Deposition Solutions



PLATINODE® SC Electrodes

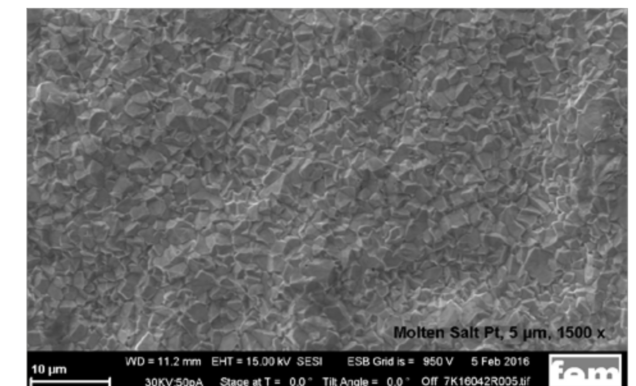


Insoluble anodes are proven to help increase process efficiency, reduce process costs, environmental impact and process control efforts in plating tools for advanced packaging. The key differentation of Umicore´s PLATINODE® is the unique layer performance due to the manufacturing method using a molten salt electrolyte allowing ultra-high purity, low porosity and best ductility even at high Pt layer thicknesses.

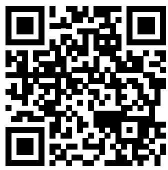
- Function: providing best-in-class ductility and chemical resistance due to unique HTE™ coating of electrode
- Customized designs, contact materials and coatings
- Fully integrated production and clean room packaging: Built-to-Order or series
- Insoluble anodes and cathodes in qualification for several WLP/PLP ECD Tools

PLATINODE® SC PtTi	PLATINODE® SC MMO
Molten salt deposited Pt on Ti substrate	Developed for low organic consumption
Developed for high ASD, predictable lifetime and outmost current distribution accuracy	End of lifetime characterized by end of electrocatalytic function and wear rate
Pt thickness can be measured / correlated to lifetime	Thickness cannot be measured / correlated to lifetime

SEM
Surface morphology 5000x



Passion for perfect surfaces



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中国江苏省苏州市吴江经济技术开发区

Established in 2012 to provide innovative products and processes to semiconductor advanced packaging

multiple patents in the field of Cu plating additives for advanced packaging

R&D, manufacturing and QA/QC located in Suzhou China, ISO 9001 and ISO 14001 certified

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UMICORE S.A. has 11.150 employees globally, €3,4 bn Revenues were generated 2019 via 50 Sites

Its Business Unit Electroplating is a segment leader in precious metals electroplating

International Set-Up for manufacturing, quality control, sales, marketing and logistics in the field of semiconductors